

Enhanced Wettability Multi use paste

EVASOL 1001 SERIES

Advanced wettability with long lasting stability suitable for various conditions of SMT.

LEAD-FREE SOLDER
EVASOL
鉛フリーはんだエバソル®



Advanced Wettability

Higher heat resistance can reduce defect of non-wetting and non-melting.

Long lasting stability

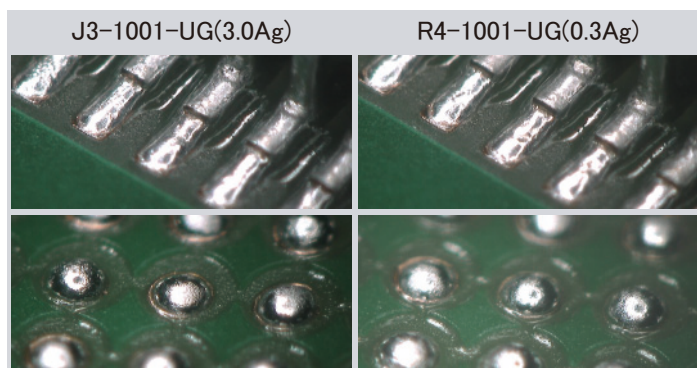
With new technology of controlling activator, stable at long time printing and transportation.

Also match for Low Ag alloy

With these new features, can use low Ag type alloy similar to usual SAC305 type alloy and help to reduce the cost.

Good wettability

● High temperature preheating test

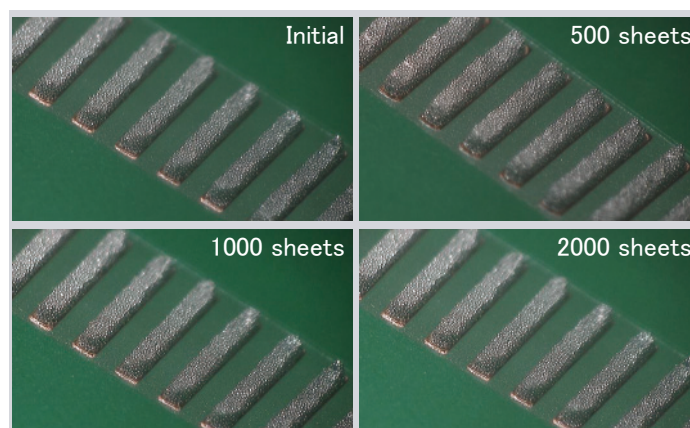


Good wettability in severe conditions

Condition : Atmospheric
Pre heat : 200°C
120 seconds
Component : 0.4mm pitch QFP
φ 0.30mm dot

Good stability on continuous printing

● Confirmation of the shape of the printed solder paste

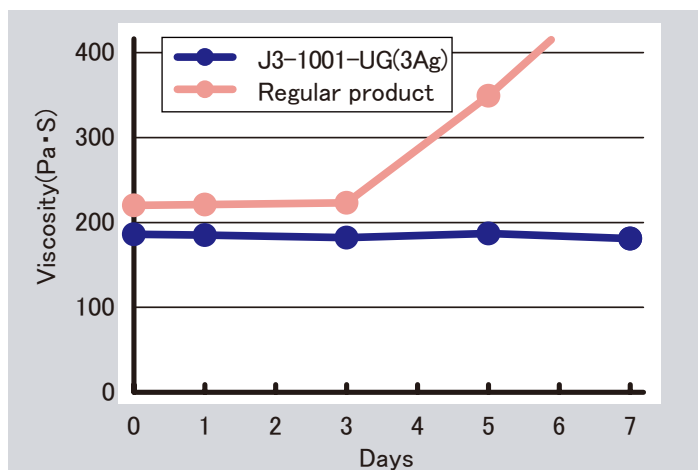


Stable shape after long time printing

J3-1001-UG (3Ag)
0.4mm pitch QFP
Stencil thickness: 0.12mm

Good transportability

● 35°C deterioration test



Prevent quality deterioration during transportation

Characteristics

Test items	Characteristics		Test method
Alloy type	J3 R4	Sn-Ag3.0-Cu0.5 Sn-Ag0.3-Cu0.7	JIS Z 3910
Flux type	MIL-RMA		—
Powder particle size(μ m)	38~20		JIS Z 8801
Flux contents(%)	12.0±1.0		JIS Z 3197 8.1.2
Halide contents(%)	Less than 0.02		JIS Z 3197 8.4.1
Viscosity test(Pa·s)	190±30		JIS Z 3284
Dryness test	Passed		JIS Z 3197 8.5.1
Flux solution resistivity(Ω m)	More than 1000		JIS Z 3197 8.1.1
Copper plate corrosion	No corrosion		JIS Z 3197 8.4.1
Copper mirror corrosion	No corrosion		JIS Z 3197 8.4.2
Insulation resistance(Ω)	More than5.0 × 10 ⁸		JIS Z 3197 8.5.3 (85°C85%RH)
Electrochemical migration	No migration		
Validity period	6 month from production date		0~10°C, Refrigerated

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